

Product/ Process Change Notification

1. PCN No.:	QPCN13010
2. Subject:	<i>D3K package soldering process change</i>
3. To:	<i>All customers involved</i>
4. Issued by:	<i>HQ(Headquarters) QRA Owen Wang</i>
5. Issue date:	<i>13-Sep-2013</i>
6. Proposed first ship date for change:	<i>13-Dec-2013</i>
7. Affected Product Identification	
<i>See attached detailed Part-No. list.</i>	
8. Change Description : (OLD Vs. NEW Comparison)	
Old:	New:
<ul style="list-style-type: none"> ➤ <i>Manual soldering process.</i> ➤ <i>Lead-frame for manual</i> ➤ <i>See attached comparison report.</i> 	<ul style="list-style-type: none"> ➤ <i>Automatic soldering process.</i> ➤ <i>Lead-frame for automation.</i> ➤ <i>See attached comparison report.</i>
9. Reason for Change:	
<i>To increase production capacity and upgrade manual soldering to automation die attached process.</i>	
10. Anticipated Impact: (form, fit, function, quality or reliability)	
1. Product outline: 2. Inner construction changed: 3. Electrical specifications: 4. Reliability performance: 5. Data sheet: 6. Packing code (order code): 7. Identification/Traceability:	<i>Not applicable</i> <i>Yes, lead-frame structure change</i> <i>No change</i> <i>No change</i> <i>Not applicable</i> <i>No change</i> <i>By date code and ordering code</i>
11. Qualification plan/result:	
Refer to Comparison report <i>See attached</i>	
12. Sample availability Date:	<i>18-Oct-2013</i>
13. Tentative implementation date:	<i>18-Oct-2013</i>
14. Remarks	
15. Customer feedback required latest: (should we receive no feedback; the change will be deemed as accepted!)	18-Oct-2013
16. Approved by:	<i>Quayer Chen</i>